

SSM2160/SSM2161—SPECIFICATIONS

ELECTRICAL SPECIFICATIONS ($V_S = \pm 5\text{ V}$, $A_V = 0\text{ dB}$, $0\text{ dBu} = 0.775\text{ Vrms}$, $V_{IN} = 0\text{ dBu}$, $f_{\text{AUDIO}} = 1\text{ kHz}$, $f_{\text{CLK}} = 250\text{ kHz}$, $R_L = 10\text{ k}\Omega$, $-40^\circ\text{C} < T_A < +85^\circ\text{C}$, unless otherwise noted. Typical specifications apply at $T_A = +25^\circ\text{C}$.)

Parameter	Conditions	Min	Typ	Max	Units
AUDIO PERFORMANCE					
Noise	$V_{IN} = \text{GND}$, 20 kHz Bandwidth		-100		dBu
Headroom	Clip Point = 1% THD+N		+10		dBu
Total Harmonic Distortion Plus Noise	2nd and 3rd Harmonics Only $A_V = 0\text{ dB}$		0.008	TBD	%
	$A_V = -10\text{ dB}$		0.02	TBD	%
Channel Separation	Any Channel to Another		80		dB
ANALOG INPUT					
Input Offset Voltage			10		mV
Input Impedance			10		k Ω
GAIN CONTROL ELEMENTS					
Default Step Size – Master	$A_{V\text{MASTER}} = 0\text{ dB to } -60\text{ dB}$		1.0		dB
Default Step Size – Channel	$A_{V\text{CHANNEL}} = 0\text{ dB to } +20\text{ dB}$		1.0		dB
Gain Error	Relative to Same Channel $A_{V\text{MASTER}} = 0\text{ dB}$			0.25	dB
	$A_{V\text{MASTER}} = -20\text{ dB}$			0.25	dB
	$A_{V\text{MASTER}} = -40\text{ dB}$			1	dB
	$A_{V\text{MASTER}} = -60\text{ dB}$			2	dB
Gain Match Error	Channel-to-Channel; Same Level Setting $A_{V\text{MASTER}} = 0\text{ dB}$			0.25	dB
	$A_{V\text{MASTER}} = -20\text{ dB}$			0.25	dB
	$A_{V\text{MASTER}} = -20\text{ dB}, A_{V\text{CH}} = +20\text{ dB}$			0.25	dB
	$A_{V\text{MASTER}} = -40\text{ dB}$			1	dB
	$A_{V\text{MASTER}} = -60\text{ dB}$			2	dB
Power On Mute Attenuation	$V_{IN} = +10\text{ dBu}$		-100		dB
ANALOG OUTPUT					
Output Impedance			5		Ω
Mute Output Impedance			5		Ω
Output Current			± 2		mA
Minimum Resistive Load Drive			1		k Ω
Maximum Capacitive Drive			TBD		pF
Offset Voltage	Channel Muted		10		mV
CONTROL SECTION					
Logic Input LO				0.8	V
Logic Input HI		2.0			V
Logic Input Current	Logic LO or HI		1		μA
Clock Frequency		1		2000	kHz
Timing Characteristics	See Timing Diagram				
ANALOG COMMON OUTPUT					
Output Voltage	See Note 1	-5		+5	%
Output Impedance			5.0		Ω
POWER SUPPLIES					
Supply Voltage Range	Dual Supply	± 4		± 15	V
	Single Supply	+8		+15	V
Supply Current	Positive		17	28	mA
	Negative		17	28	mA
Power Supply Rejection Ratio	Dual Supply		TBD		dB

NOTES

¹Analog Common Output is used in single supply applications. It is nominally half the voltage between V_+ and V_- , e.g., $\frac{V_+ - (V_-)}{2}$.

Specifications subject to change without notice.

ABSOLUTE MAXIMUM RATINGS¹

Supply Voltage

Dual Supply ±18 V

Single Supply +18 V

Analog Input Voltage ±V_S

Analog Output Voltage ±V_S

Logic Input Voltage ±V_S

Operating Temperature Range -40°C to +85°C

Storage Temperature -65°C to +150°C

Junction Temperature (T_J) +150°C

Lead Temperature (Soldering, 60 sec) +300°C

THERMAL CHARACTERISTICS

Thermal Resistance²

24-Pin Plastic DIP (SSM2160)

θ_{JA} 60°C/W

θ_{JC} 30°C/W

24-Pin SOIC (SSM2160)

θ_{JA} 71°C/W

θ_{JC} 23°C/W

20-Pin Plastic DIP (SSM2161)

θ_{JA} 65°C/W

θ_{JC} 26°C/W

20-Pin SOIC (SSM2161)

θ_{JA} 84°C/W

θ_{JC} 24°C/W

ESD RATINGS

883 (Human Body) Model TBD kV

EIAJ Model TBD V

NOTES

¹Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

²θ_{JA} is specified for worst-case conditions, i.e., θ_{JA} is specified for device in socket for P-DIP and device soldered in circuit board for SOIC package.

ORDERING GUIDE

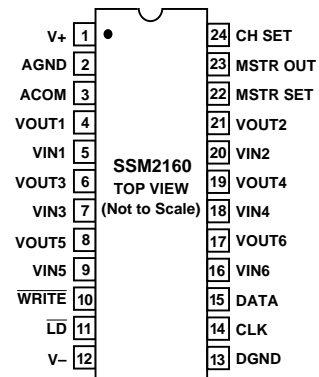
Model	Temperature Range	Package Option
SSM2160P	-40°C to +85°C	24-Lead Plastic DIP
SSM2160S	-40°C to +85°C	24-Lead SOL
SSM2160S-REEL	-40°C to +85°C	24-Lead SOL
SSM2161P	-40°C to +85°C	20-Lead Plastic DIP
SSM2161S	-40°C to +85°C	20-Lead SOL
SSM2161S-REEL	-40°C to +85°C	20-Lead SOL

CAUTION

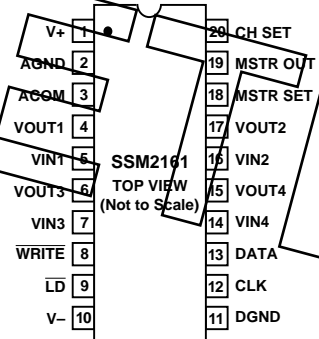
ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the SSM2160/SSM2161 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.

PIN CONFIGURATIONS

24-Lead Epoxy DIP and SOIC



20-Lead Epoxy DIP and SOIC



SSM2160/SSM2161

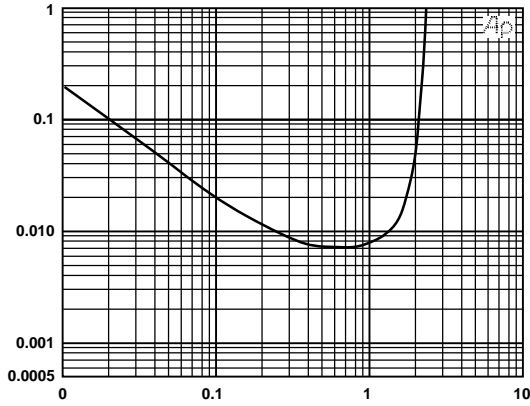


Figure 1. THD vs. Amplitude (Gain = 0 dB, $V_{SY} = \pm 5 V$)

MASTER DAC:	0 0 0 0 0 0	-127 dB
	1 1 1 1 1 1	0 dB
CHANNEL DACs:	0 0 0 0	+31 dB
	1 1 1 1	0 dB

Figure 2. Data Settings for DACs

SELECTION	ADDRESS MODE				DATA MODE														
	ADDRESS				DATA														
	MSB	MSB	LSB	LSB	MSB	MSB	LSB	LSB											
7-BIT MASTER DAC	1	X	X	X	0	0	0	0											
5-BIT CHANNEL DAC 1	1	X	X	X	0	0	0	1	X										
5-BIT CHANNEL DAC 2	1	X	X	X	0	1	0	0	1	X									
5-BIT CHANNEL DAC 3	1	X	X	X	0	1	1	0	1	X									
5-BIT CHANNEL DAC 4	1	X	X	X	1	0	0	0	1	X									
5-BIT CHANNEL DAC 5	1	X	X	X	1	0	1	0	1	X									
5-BIT CHANNEL DAC 6	1	X	X	X	1	1	0	0	1	X									
NO DAC SELECTED	1	X	X	X	1	1	1	0	1	X									

X = "DON'T CARE"
 SHADED AREA IS DATA
 0 = MUTE,
 1 = UN-MUTE

Figure 3. Interface Characteristics, DAC Address/Data Decoding Truth Table

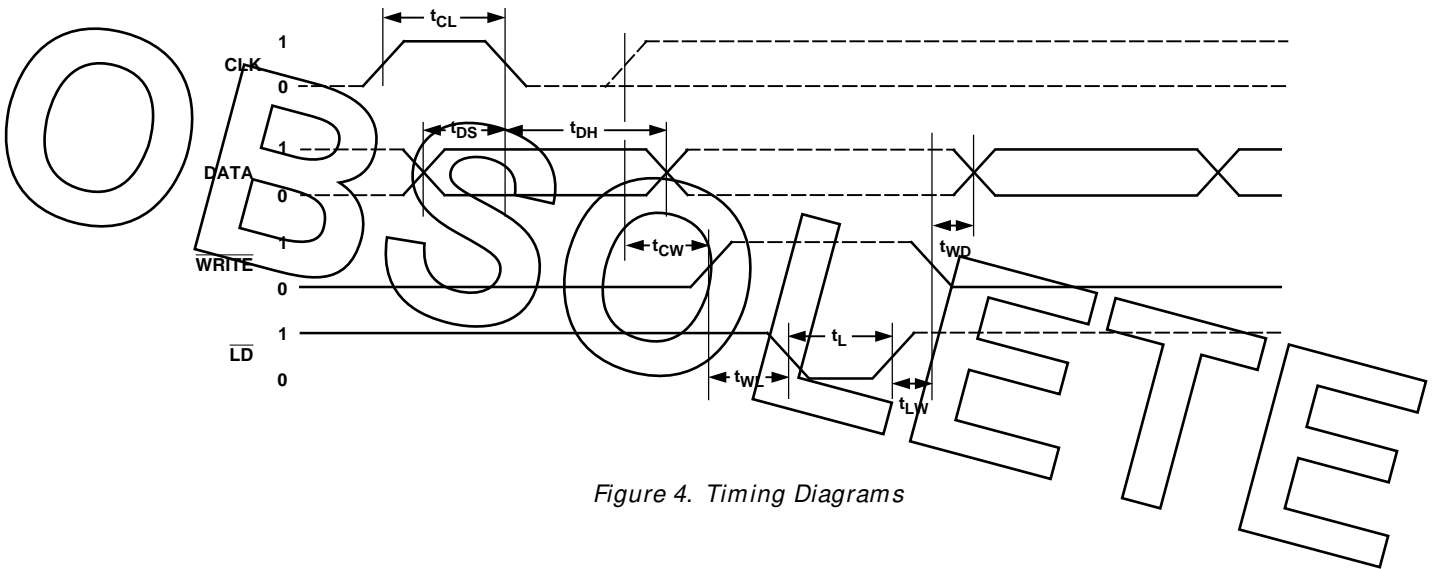
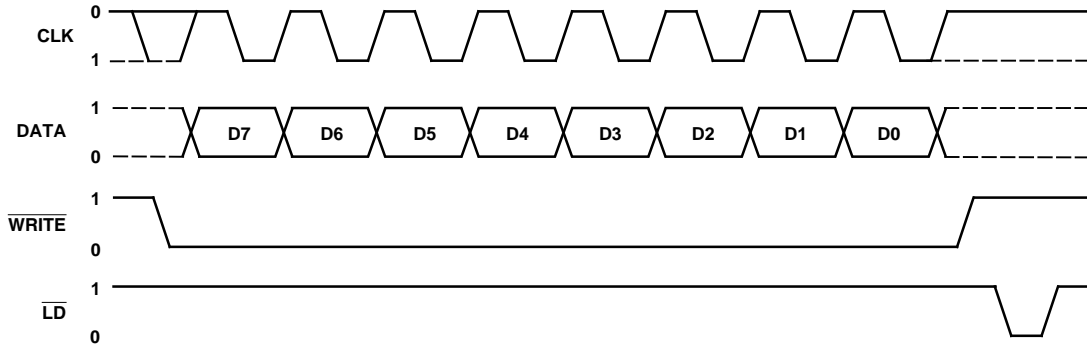


Figure 4. Timing Diagrams

NOTES

1. An idle HI (CLK-H) or idle LO (CLK-LO) clock may be used. Data is latched on the negative edge.
2. For **SPI** or **microwire** three-wire bus operation, tie \overline{LD} to \overline{WRITE} and use \overline{WRITE} pulse to drive both pins. (This generates an automatic internal \overline{LD} signal.)
3. If an idle HI clock is used, t_{CW} and t_{WL} are measured from the final negative transition to the idle state.
4. The first data byte selects an address (MSB HI), and subsequent MSB LO states set gain levels. Refer to the Address/Data Decoding Truth Table.
5. Data must be sent MSB first.
6. The SSM2160/SSM2161 will power up with all channel outputs muted, thus preventing "start-up blasting." To insure a smooth start-up, data should be sent to first initialize the Master DAC, then to set the individual channel DAC levels.

Table I. Timing Description

Timing Symbol	Description	Typical Time (ns)
t_{CL}	Input Clock Pulse Width	TBD
t_{DS}	Data Setup Time	TBD
t_{DH}	Data Hold Time	TBD
t_{CW}	Negative CLK-LO Edge to End of Write	TBD
t_{LW}	End of Load Pulse to Next Write	TBD
t_{WD}	Start of Write to Data	TBD
t_{WL}	End of Write to Start of Load	TBD
t_L	Load Pulse Width	TBD

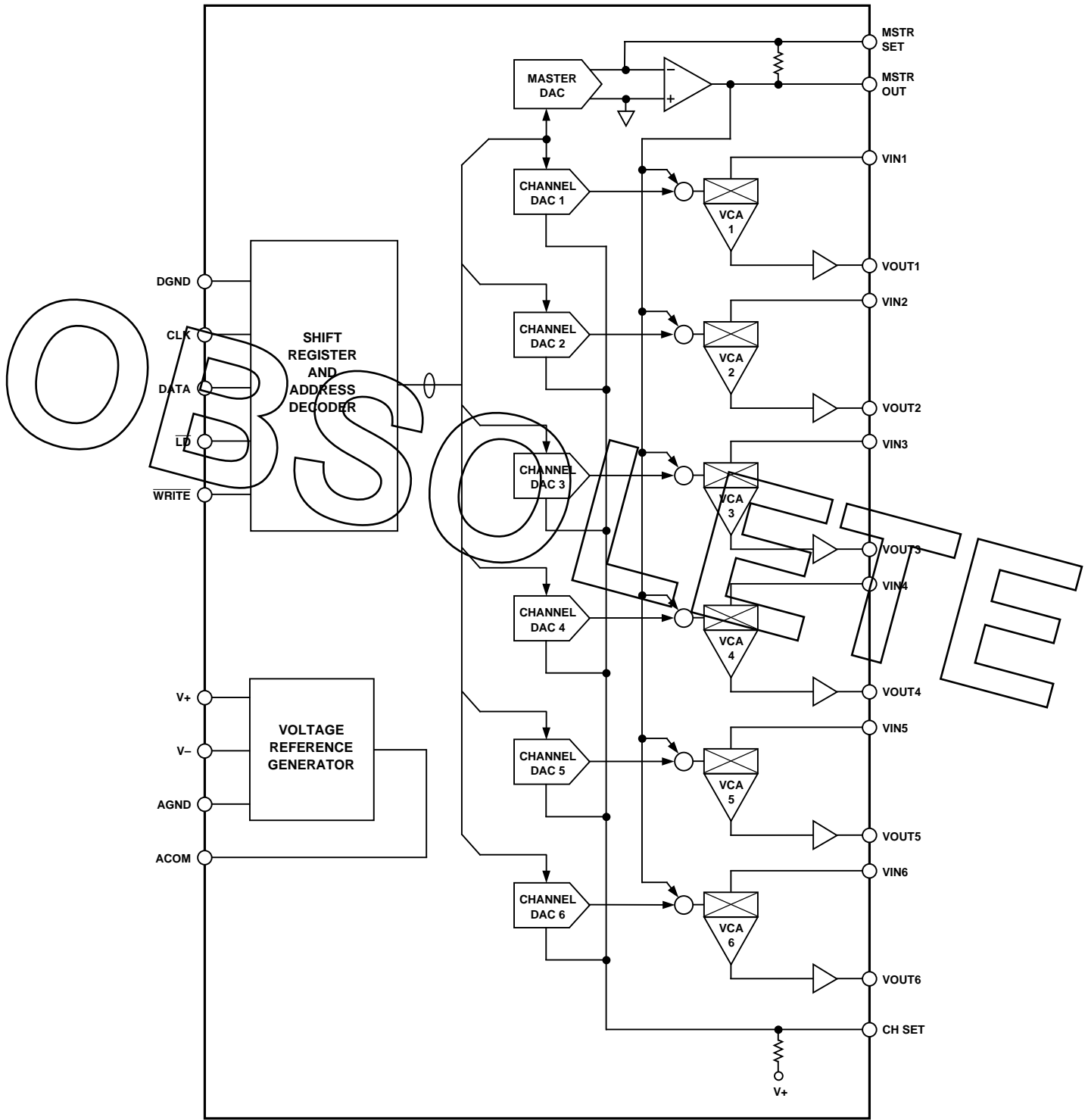
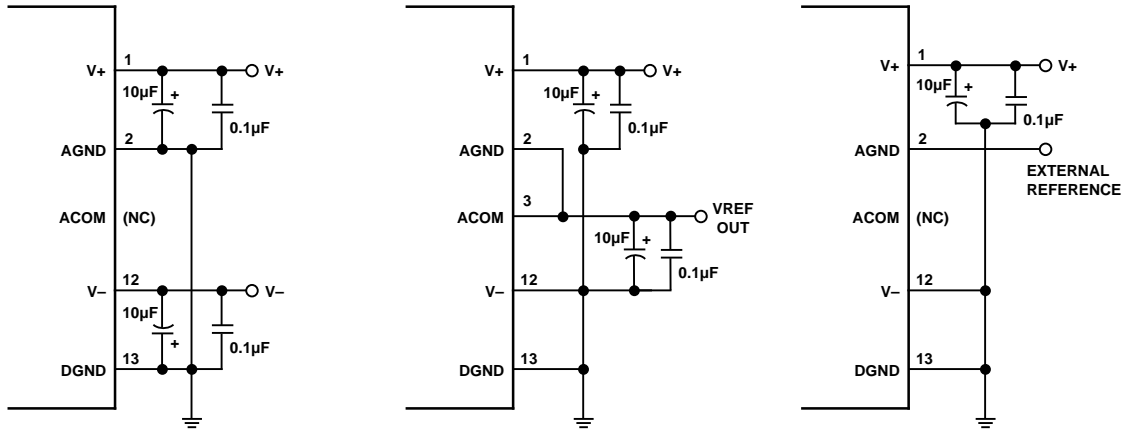


Figure 5. SSM2160 Functional Diagram (SSM2161 Same but with Channels 5 and 6 Omitted)

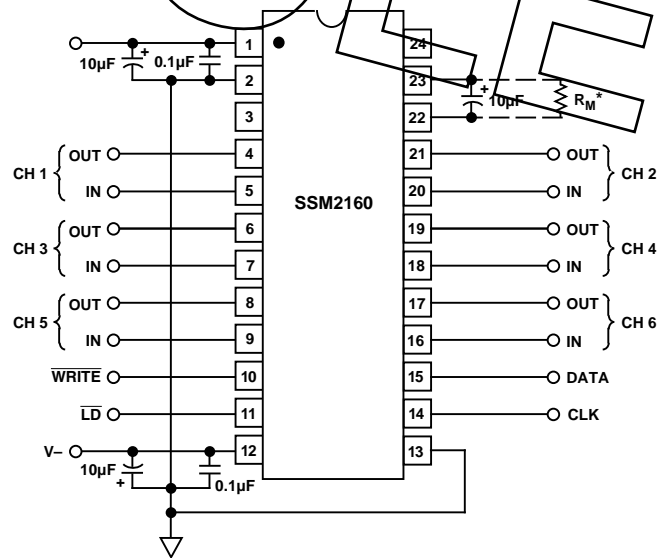


a. Dual Supply

b. Single Supply

c. Single Supply Using External Reference

Figure 6. SSM2160 Power Supply Connections



To change step sizes: Master DAC:
 *Use formula $R_M = 1400X/(1-X)$:
 where "X" equal desired step size in dB.
 Note: Step sizes indicated are approximate.

Figure 7. Typical Application Circuit (Dual Supply)